

Agenda Wednesday, November 18, 2009

Agenda Wednesday, November 18, 2009		
Time	Topic	Presenter
8:00-8:30	R E G I S T R A T I O N	
8:30-8:45	Welcome and logistical remarks	Bruce Chamberlin
Session Chair- Eddie Kobeda, Program Director, IBM Integrated Supply Chain Engineering		
8:45-9:15	ISC Keynote speaker	Sophie Bechu-IBM VP ISC Engineering
9:15-10:00	IBM System and Packaging Overview (I, p, z, x, Blade servers, and Super computers	Harald Pross, Pravin Patel-IBM
10:00-10:30	IBM Technology Bottleneck Analysis	Hubert Harrer, et al- IBM
10:30-11:00	B R E A K	
11:00-11:30	Endicott Interconnect Technologies Overview	Voya Markovich- EI
11:30-noon	Matched terminated stubs using embedded resistors	George Dudnikov-Sanmina
noon-1:00	L U N C H	
Session Chair- Dale Becker, STSM, Hardware Architect System & Technology Group		
1:00-1:30	Hydrolytic Stability of Glass Epoxy Interfaces	Ray Pearson-Lehigh
1:30-2:00	IBM PCB Pb-free Transition	Marie Cole-IBM
2:00-2:30	Laminate Study Group Fracture Toughness Work	Brett Krull- IBM
2:30-2:45	IBM Faculty Research Award	Johannes Windeln-IBM
2:45-3:15	B R E A K	
3:15-4:15	Panel Discussion- Loss characteristics-Discuss benefits of stub reduction techniques, copper roughness, spread glass vs. rotated image, etc	Moderator- Roger Krabbenhoft
4:15-6:00	Poster Session	

Agenda Thursday, November 19, 2009

Agenda Thursday, November 19 2009		
Time	Topic	Presenter
8:00-8:30	Check-in	
Session Chair- Jason Chou, Printed Circuit Board Engineering, PQE		
8:30-9:00	STG Keynote speaker	John Birtles- Director, System z Portfolio manager
9:00-9:30	Electrical characterization	Brian Butler- Interbotics
9:30-10:00	Newly Developed low-transmission-loss multilayer materials for PWBs applied to high GHz bands	Mr. Kenichi Ikeda- Hitachi
10:00-10:30	B R E A K	
10:30-11:00	Pb Free HASL	Matt Kelly- IBM
11:00-11:30	Environmental Laws Affecting PCB (REACH, RoHS, etc)	John Quick- IBM
11:30-noon	Developing, characterizing, and achieving mass production for mid & low loss PCB materials for Pb-free using IBM driven methodologies	Joe Beers- GCE
Noon-1:00	L U N C H	
Session Chair- Sunil Nigam, xSeries PCB Technical Program Manager, ISC		
1:00-1:30	IBM Engineering Services	Eric Kline- IBM
1:30-2:00	Optical Backplane Manufacturing Development Status	Marika Immonen- DMC
2:00-2:30	IBM Optical PCB Development Findings	Marc Taubenblatt- IBM
2:30-3:00	B R E A K	
3:00-4:00	Panel Discussion- Mechanical control- PCB planarity, warpage, thickness control, feature location- PCB technology team giving feedback to design group	Moderator- Bill Brodsky
4:00-4:14	Closing Remarks	Mark Morizio, Director ISC Engineering